



RELIABILITY REPORT
FOR
MAX6639FAEE+
PLASTIC ENCAPSULATED DEVICES

November 10, 2008

MAXIM INTEGRATED PRODUCTS

120 SAN GABRIEL DR.
SUNNYVALE, CA 94086

Approved by
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Conclusion

The MAX6639FAEE+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

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I. Device Description

A. General

The MAX6639 monitors its own temperature and one external diode-connected transistor or the temperatures of two external diode-connected transistors, typically available in CPUs, FPGAs, or GPUs. The 2-wire serial interface accepts standard System Management Bus (SMBus(tm)) write byte, read byte, send byte, and receive byte commands to read the temperature data and program the alarm thresholds. Temperature data can be read at any time over the SMBus, and three programmable alarm outputs can be used to generate interrupts, throttle signals, or overtemperature shutdown signals. The temperature data is also used by the internal dual-PWM fan-speed controller to adjust the speed of up to two cooling fans, thereby minimizing noise when the system is running cool, but providing maximum cooling when power dissipation increases. Speed control is accomplished by tachometer feedback from the fan, so that the speed of the fan is controlled, not just the PWM duty cycle. Accuracy of speed measurement is $\pm 4\%$. The MAX6639 is available in 16-pin QSOP and 16-pin thin QFN 5mm x 5mm packages. It operates from 3.0V to 3.6V and consumes just 500 μ A of supply current.

II. Manufacturing Information

A. Description/Function:	2-Channel Temperature Monitor with Dual, Automatic, PWM Fan-Speed Controller
B. Process:	B8
C. Number of Device Transistors:	
D. Fabrication Location:	Texas
E. Assembly Location:	Carsem Malasia, ATP Philippines, Unisem Malaysia
F. Date of Initial Production:	April 18, 2008

III. Packaging Information

A. Package Type:	16-pin QSOP
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive Epoxy
E. Bondwire:	Gold (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-9000-1146
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Ja:	120°C/W
K. Single Layer Theta Jc:	37°C/W
L. Multi Layer Theta Ja:	103.7°C/W
M. Multi Layer Theta Jc:	37°C/W

IV. Die Information

A. Dimensions:	86 X 116 mils
B. Passivation:	Si ₃ N ₄ /SiO ₂ (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Aluminum/Cu (Cu = 0.5%)
D. Backside Metallization:	None
E. Minimum Metal Width:	0.8 microns (as drawn)
F. Minimum Metal Spacing:	0.8 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO ₂
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

A. Quality Assurance Contacts:	Ken Wendel (Director, Reliability Engineering) Bryan Preeshl (Managing Director of QA)
B. Outgoing Inspection Level:	0.1% for all electrical parameters guaranteed by the Datasheet. 0.1% For all Visual Defects.
C. Observed Outgoing Defect Rate:	< 50 ppm
D. Sampling Plan:	Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4340 \times 48 \times 2} \quad (\text{Chi square value for MTTF upper limit})$$

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$$\lambda = 22.4 \times 10^{-9}$$

$\lambda = 22.4$ F.I.T. (60% confidence level @ 25°C)

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly 1000 hour life test monitors on its processes. This data is published in the Product Reliability Report found at <http://www.maxim-ic.com/>. Current monitor data for the B8 Process results in a FIT Rate of 2.71 @ 25C and 17.30 @ 55C (0.8 eV, 60% UCL)

B. Moisture Resistance Tests

The industry standard 85°C/85%RH or HAST testing is monitored per device process once a quarter.

C. E.S.D. and Latch-Up Testing

The TS58-1 die type has been found to have all pins able to withstand a HBM transient pulse of +/-1000 V per Mil-Std 883 Method 3015.7. Latch-Up testing has shown that this device withstands a current of +/-250 mA.

Table 1
Reliability Evaluation Test Results

MAX6639FAEE+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES
Static Life Test (Note 1)	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	48	0
Moisture Testing (Note 2) 85/85	Ta = 85°C RH = 85% Biased Time = 1000hrs.	DC Parameters & functionality	77	0
Mechanical Stress (Note 2) Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters & functionality	77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.

Note 2: Generic Package/Process data